



RF360
Europe GmbH

Data sheet

SAW duplexer
Small cell & femtocell
LTE band 5

| | |
|----------------|-----------------|
| Series/type: | B8013 |
| Ordering code: | B39881B8013P810 |

| | |
|-------|-------------------|
| Date: | December 11, 2018 |
|-------|-------------------|

| | |
|----------|-----|
| Version: | 2.9 |
|----------|-----|

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A Qualcomm – TDK Joint Venture

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1 Application

- Low-loss SAW duplexer for LTE small cell systems (Band 5)
- Usable pass band 25MHz
- RX=uplink=824-849MHz
- TX=downlink=869-894MHz

2 Features

- Industrial grade qualified family
- Package size $2.5 \pm 0.1 \text{ mm} \times 2.0 \pm 0.1 \text{ mm}$
- Package height 0.5 mm (max.)
- Approximate weight 0.01 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)

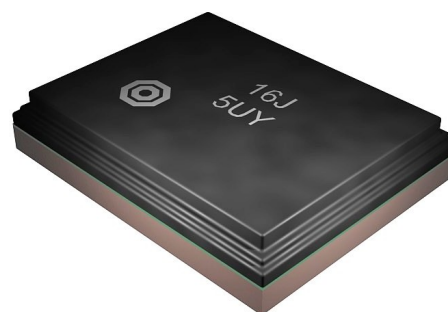
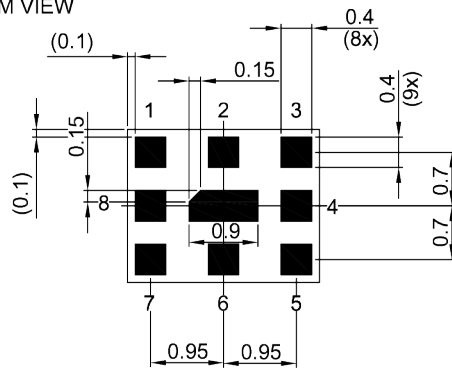


Figure 1: Picture of component with example of product marking.

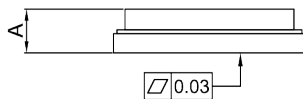
3 Package

BOTTOM VIEW

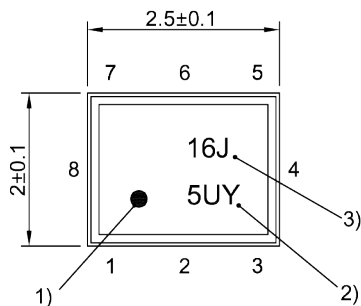


Pad and pitch tolerance ± 0.05

SIDE VIEW

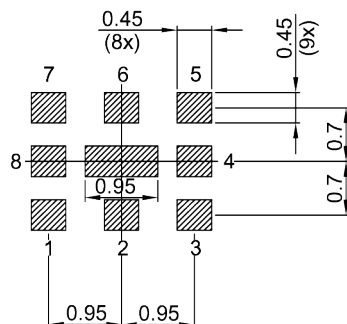


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern
THRU VIEW



Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.5 mm (max.). See Sec. Package information (p. 26).

4 Pin configuration

- 1 TX
- 3 RX
- 6 ANT
- 2, 4, 5, 7, 8, 9 Ground

5 Matching circuit

■ $L_{p6} = 8.7 \text{ nH}$

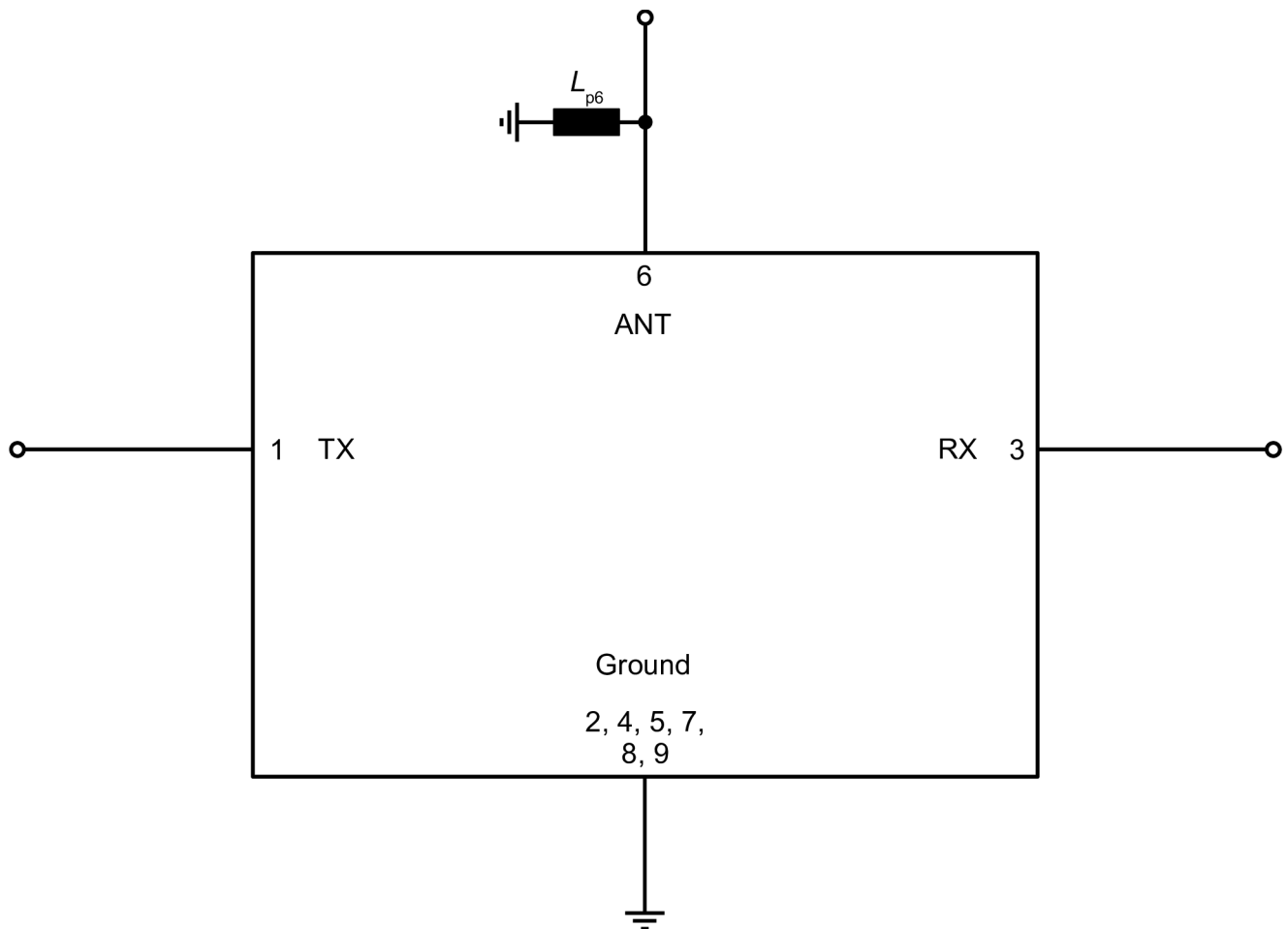


Figure 3: Schematic of matching circuit.

6 Characteristics

6.1 TX – ANT

| | | |
|-------------------------------------|-------------------|--|
| Temperature range for specification | T_{SPEC} | = -10 °C ... +85 °C |
| TX terminating impedance | Z_{TX} | = 50 Ω |
| ANT terminating impedance | Z_{ANT} | = 50 Ω with par. 8.7 nH ¹⁾ |
| RX terminating impedance | Z_{RX} | = 50 Ω |

| Characteristics TX – ANT | | | | min. for T_{SPEC} | typ. @ +25 °C | max. for T_{SPEC} | |
|--------------------------------|------------------|---|--|-------------------------------|------------------|-------------------------------|-----|
| Center frequency | | f_{C} | | — | 881.5 | — | MHz |
| Average insertion attenuation | | $\alpha_{\text{INT,avg}}$ ²⁾ | | — | 1.9 | 2.5 | dB |
| | 869... 874 | MHz | | — | 1.5 | 2.5 | dB |
| | 874... 889 | MHz | | — | 1.7 | 2.5 | dB |
| | 889... 894 | MHz | | — | 1.9 | 2.5 | dB |
| Maximum insertion attenuation | | α_{max} | | — | 1.9 | 2.5 ³⁾ | dB |
| | 869... 894 | MHz | | — | 0.6 | 1.3 ⁴⁾ | dB |
| Amplitude ripple (p-p) | | $\Delta\alpha$ | | — | 0.6 | 1.3 ⁴⁾ | dB |
| | 869... 894 | MHz | | — | 1.9 | 2.1 ⁵⁾ | dB |
| Maximum VSWR | | VSWR _{max} | | — | 1.8 | 2.1 ⁵⁾ | dB |
| @ TX port | 869... 894 | MHz | | — | 1.4 | 3.5 | % |
| @ ANT port | 869... 894 | MHz | | — | 52 | 59 | dB |
| Maximum error vector magnitude | | EVM _{max} ⁶⁾ | | — | 45 | 58 | dB |
| | 871.4... 891.6 | MHz | | — | 35 | 59 | dB |
| Minimum attenuation | | α_{min} | | — | 40 | 59 | dB |
| | 824... 849 | MHz | | — | 40 | 57 | dB |
| | 1574.4... 1576.4 | MHz | | — | 40 | 55 | dB |
| | 1602.5... 1615.5 | MHz | | — | 40 | 50 | dB |
| | 1710... 1788 | MHz | | — | 37 | 47 | dB |
| | 1850... 1910 | MHz | | — | 35 | 49 | dB |
| | 1920... 1980 | MHz | | — | | | |
| | 2400... 2484 | MHz | | — | | | |
| | 2607... 2682 | MHz | | — | | | |
| | 3476... 3576 | MHz | | — | | | |

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated over 5 MHz.

³⁾ Specification for IL_{max} is 2.6dB for -20 °C ... +85 °C.

⁴⁾ Specification for AR is 1.4dB for -20 °C ... +85 °C.

⁵⁾ Specification for VSWR is 2.2 for -20 °C ... +85 °C.

⁶⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

| | | |
|-------------------------------------|-------------------|--|
| Temperature range for specification | T_{SPEC} | = -40 °C ... +95 °C |
| TX terminating impedance | Z_{TX} | = 50 Ω |
| ANT terminating impedance | Z_{ANT} | = 50 Ω with par. 8.7 nH ¹⁾ |
| RX terminating impedance | Z_{RX} | = 50 Ω |

| Characteristics TX – ANT | | | min. for T_{SPEC} | typ. @ +25 °C | max. for T_{SPEC} | |
|---------------------------------------|------------------|---|-------------------------------|------------------|-------------------------------|-----|
| Center frequency | | f_{C} | — | 881.5 | — | MHz |
| Average insertion attenuation | | $\alpha_{\text{INT,avg}}$ ²⁾ | | | | |
| | 869... 874 | MHz | — | 1.9 | 3.0 | dB |
| | 874... 889 | MHz | — | 1.5 | 3.0 | dB |
| | 889... 894 | MHz | — | 1.7 | 3.0 | dB |
| Maximum insertion attenuation | | α_{max} | | | | |
| | 869... 894 | MHz | — | 1.9 | 3.0 | dB |
| Amplitude ripple (p-p) | | $\Delta\alpha$ | | | | |
| | 869... 894 | MHz | — | 0.6 | 1.7 | dB |
| Maximum VSWR | | VSWR_{max} | | | | |
| @ TX port | 869... 894 | MHz | — | 1.9 | 2.3 | |
| @ ANT port | 869... 894 | MHz | — | 1.8 | 2.3 | |
| Maximum error vector magnitude | | EVM_{max} ³⁾ | | | | |
| | 871.4... 891.6 | MHz | — | 1.4 | 4.0 | % |
| Minimum attenuation | | α_{min} | | | | |
| | 824... 849 | MHz | 52 | 59 | — | dB |
| | 1574.4... 1576.4 | MHz | 45 | 58 | — | dB |
| | 1602.5... 1615.5 | MHz | 35 | 59 | — | dB |
| | 1710... 1788 | MHz | 40 | 59 | — | dB |
| | 1850... 1910 | MHz | 40 | 57 | — | dB |
| | 1920... 1980 | MHz | 40 | 55 | — | dB |
| | 2400... 2484 | MHz | 40 | 50 | — | dB |
| | 2607... 2682 | MHz | 37 | 47 | — | dB |
| | 3476... 3576 | MHz | 35 | 49 | — | dB |

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated over 5 MHz.

³⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

6.2 ANT – RX

| | | |
|-------------------------------------|------------|--|
| Temperature range for specification | T_{SPEC} | = -10 °C ... +85 °C |
| TX terminating impedance | Z_{TX} | = 50 Ω |
| ANT terminating impedance | Z_{ANT} | = 50 Ω with par. 8.7 nH ¹⁾ |
| RX terminating impedance | Z_{RX} | = 50 Ω |

| Characteristics ANT – RX | | | min. for T_{SPEC} | typ. @ +25 °C | max. for T_{SPEC} | |
|---------------------------------------|----------------|----------------------------------|------------------------|------------------|------------------------|-----|
| Center frequency | | f_C | — | 836.5 | — | MHz |
| Average insertion attenuation | | $\alpha_{INT,avg}$ ²⁾ | | | | |
| | 824... 829 | MHz | — | 2.1 | 3.1 | dB |
| | 829... 844 | MHz | — | 1.8 | 3.1 | dB |
| | 844... 849 | MHz | — | 1.7 | 3.1 | dB |
| Maximum insertion attenuation | | α_{max} | | | | |
| | 824... 849 | MHz | — | 2.6 | 3.1 ³⁾ | dB |
| Amplitude ripple (p-p) | | $\Delta\alpha$ | | | | |
| | 824... 849 | MHz | — | 1.3 | 1.8 ⁴⁾ | dB |
| Maximum VSWR | | VSWR _{max} | | | | |
| @ ANT port | 824... 849 | MHz | — | 1.9 | 2.3 ⁵⁾ | |
| @ RX port | 824... 849 | MHz | — | 2.0 | 2.3 ⁵⁾ | |
| Maximum error vector magnitude | | EVM _{max} ⁶⁾ | | | | |
| | 826.4... 846.6 | MHz | — | 3.0 | 4.5 | % |
| Minimum attenuation | | α_{min} | | | | |
| | 869... 894 | MHz | 50 | 57 | — | dB |
| | 1648... 1698 | MHz | 45 | 51 | — | dB |
| | 1840... 1870 | MHz | 40 | 48 | — | dB |
| | 1930... 1990 | MHz | 40 | 46 | — | dB |
| | 2110... 2170 | MHz | 35 | 45 | — | dB |
| | 2400... 2484 | MHz | 35 | 42 | — | dB |
| | 2472... 2547 | MHz | 35 | 41 | — | dB |
| | 3296... 3396 | MHz | 32 | 39 | — | dB |

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated over 5 MHz.

³⁾ Specification for IL_{max} is 3.2dB for -20 °C ... +85 °C.

⁴⁾ Specification for AR is 1.9dB for -20 °C ... +85 °C.

⁵⁾ Specification for VSWR is 2.4 for -20 °C ... +85 °C.

⁶⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

| | | |
|-------------------------------------|-------------------|--|
| Temperature range for specification | T_{SPEC} | = -40 °C ... +95 °C |
| TX terminating impedance | Z_{TX} | = 50 Ω |
| ANT terminating impedance | Z_{ANT} | = 50 Ω with par. 8.7 nH ¹⁾ |
| RX terminating impedance | Z_{RX} | = 50 Ω |

| Characteristics ANT – RX | | | min. for T_{SPEC} | typ. @ +25 °C | max. for T_{SPEC} | |
|---------------------------------------|----------------|---|-------------------------------|------------------|-------------------------------|-----|
| Center frequency | | f_{C} | — | 836.5 | — | MHz |
| Average insertion attenuation | | $\alpha_{\text{INT,avg}}$ ²⁾ | | | | |
| | 824... 829 | MHz | — | 2.1 | 3.8 | dB |
| | 829... 844 | MHz | — | 1.8 | 3.8 | dB |
| | 844... 849 | MHz | — | 1.7 | 3.8 | dB |
| Maximum insertion attenuation | | α_{max} | | | | |
| | 824... 849 | MHz | — | 2.6 | 3.8 | dB |
| Amplitude ripple (p-p) | | $\Delta\alpha$ | | | | |
| | 824... 849 | MHz | — | 1.3 | 2.5 | dB |
| Maximum VSWR | | VSWR_{max} | | | | |
| @ ANT port | 824... 849 | MHz | — | 1.9 | 2.5 | |
| @ RX port | 824... 849 | MHz | — | 2.0 | 2.5 | |
| Maximum error vector magnitude | | EVM_{max} ³⁾ | | | | |
| | 826.4... 846.6 | MHz | — | 3.0 | 5.0 | % |
| Minimum attenuation | | α_{min} | | | | |
| | 869... 894 | MHz | 50 | 55 | — | dB |
| | 1648... 1698 | MHz | 45 | 51 | — | dB |
| | 1840... 1870 | MHz | 40 | 48 | — | dB |
| | 1930... 1990 | MHz | 40 | 46 | — | dB |
| | 2110... 2170 | MHz | 35 | 45 | — | dB |
| | 2400... 2484 | MHz | 35 | 42 | — | dB |
| | 2472... 2547 | MHz | 35 | 41 | — | dB |
| | 3296... 3396 | MHz | 32 | 39 | — | dB |

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated over 5 MHz.

³⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

6.3 TX – RX

| | | |
|-------------------------------------|-------------------|--|
| Temperature range for specification | T_{SPEC} | = -10 °C ... +85 °C |
| TX terminating impedance | Z_{TX} | = 50 Ω |
| ANT terminating impedance | Z_{ANT} | = 50 Ω with par. 8.7 nH ¹⁾ |
| RX terminating impedance | Z_{RX} | = 50 Ω |

| Characteristics TX – RX | | | min. for T_{SPEC} | typ. @ +25 °C | max. for T_{SPEC} | |
|-------------------------|----------------|---|-------------------------------|------------------|-------------------------------|----|
| Average isolation | 824... 849 MHz | $\alpha_{\text{INT,avg}}$ ²⁾ | 52 | 58 | — | dB |
| | | | 53 | 61 | — | |
| Minimum isolation | 824... 849 MHz | α_{min} | 52 | 58 | — | dB |
| | | | 53 | 56 | — | |

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated over 5 MHz.

| | | |
|-------------------------------------|-------------------|--|
| Temperature range for specification | T_{SPEC} | = -40 °C ... +95 °C |
| TX terminating impedance | Z_{TX} | = 50 Ω |
| ANT terminating impedance | Z_{ANT} | = 50 Ω with par. 8.7 nH ¹⁾ |
| RX terminating impedance | Z_{RX} | = 50 Ω |

| Characteristics TX – RX | | | min. for T_{SPEC} | typ. @ +25 °C | max. for T_{SPEC} | |
|-------------------------|---|----------------|-------------------------------|------------------|-------------------------------|----|
| Average isolation | $\alpha_{\text{INT,avg}}$ ²⁾ | 824... 849 MHz | 52 | 58 | — | dB |
| | | 869... 894 MHz | 52 | 61 | — | dB |
| Minimum isolation | α_{min} | 824... 849 MHz | 52 | 56 | — | dB |
| | | 869... 894 MHz | 52 | 56 | — | dB |

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated over 5 MHz.

7 Maximum ratings

| | | |
|---|--|---|
| Operable temperature | $T_{OP} = -40\text{ °C} \dots +95\text{ °C}$ | |
| Storage temperature | $T_{STG}^{1)} = -40\text{ °C} \dots +95\text{ °C}$ | |
| DC voltage | $ V_{DC} ^{2)} = 0\text{ V}$ | |
| ESD voltage | | |
| | $V_{ESD}^{3)} = 100\text{ V}$ | Machine model. |
| | $V_{ESD}^{4)} = 250\text{ V}$ | Human body model. |
| Input power | P_{IN} | |
| @ TX port: 871.5 ... 891.5 MHz | 28 dBm ^{5), 6)} | 5 MHz LTE downlink signal (25 RB) for 100000 h @ 55 °C. P_{IN} 28 dBm average - 39 dBm peak Source and load impedance 50 Ω. |
| @ TX port: other frequency ranges | 10 dBm | Source and load impedance 50Ω. |
| Operating lifetime with output power at antenna 871.5 ... 891.5 MHz | $P_{OUT}^{7)} = 24\text{ dBm}$ | Continuous wave for 100000 h @ 55 °C. Source and load impedance 50Ω. |

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

³⁾ According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

⁴⁾ According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

⁵⁾ Expected lifetime according to accelerated power durability tests, and wear out models.

⁶⁾ T_{SPEC} is the ambient temperature of the PCB at component position. Specified min./max values from section 6 "characteristics" for maximum input power 28dBm are valid for temperature up to 55°C.

⁷⁾ According to accelerated high temperature operating life (HTOL) test.

8 Transmission coefficients

8.1 TX – ANT

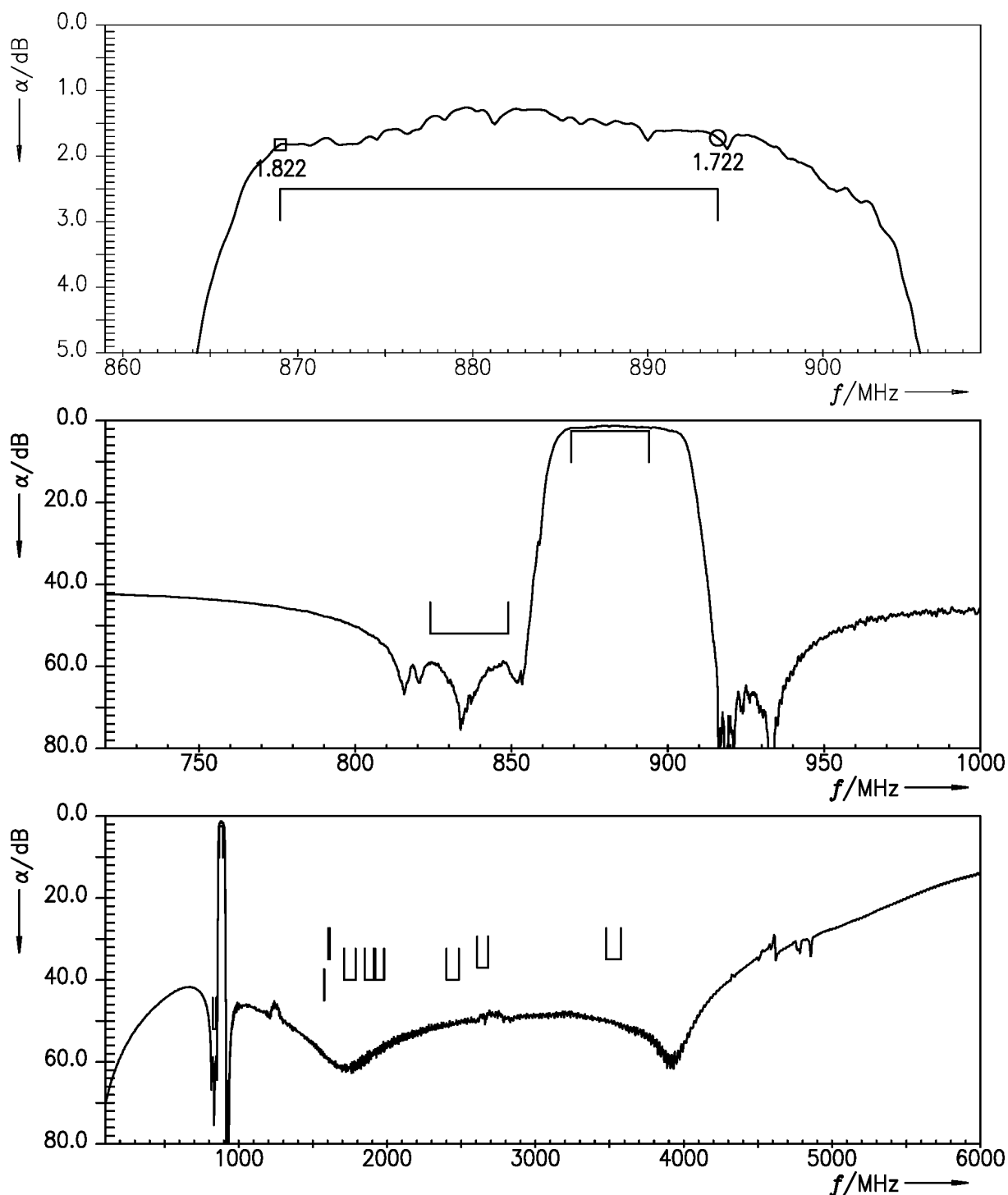


Figure 4: Attenuation TX – ANT.

8.2 ANT – RX

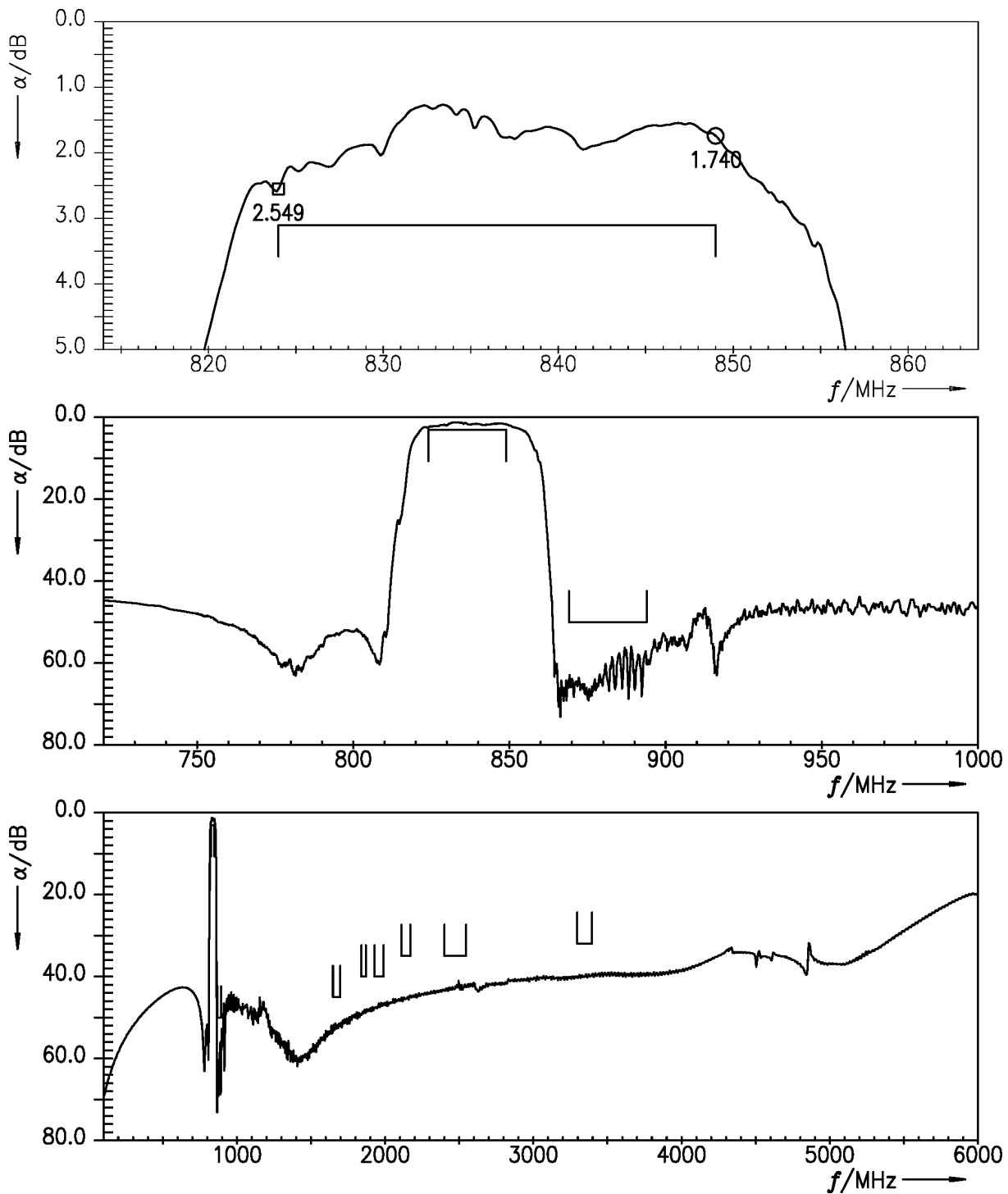


Figure 5: Attenuation ANT – RX.

8.3 TX – RX

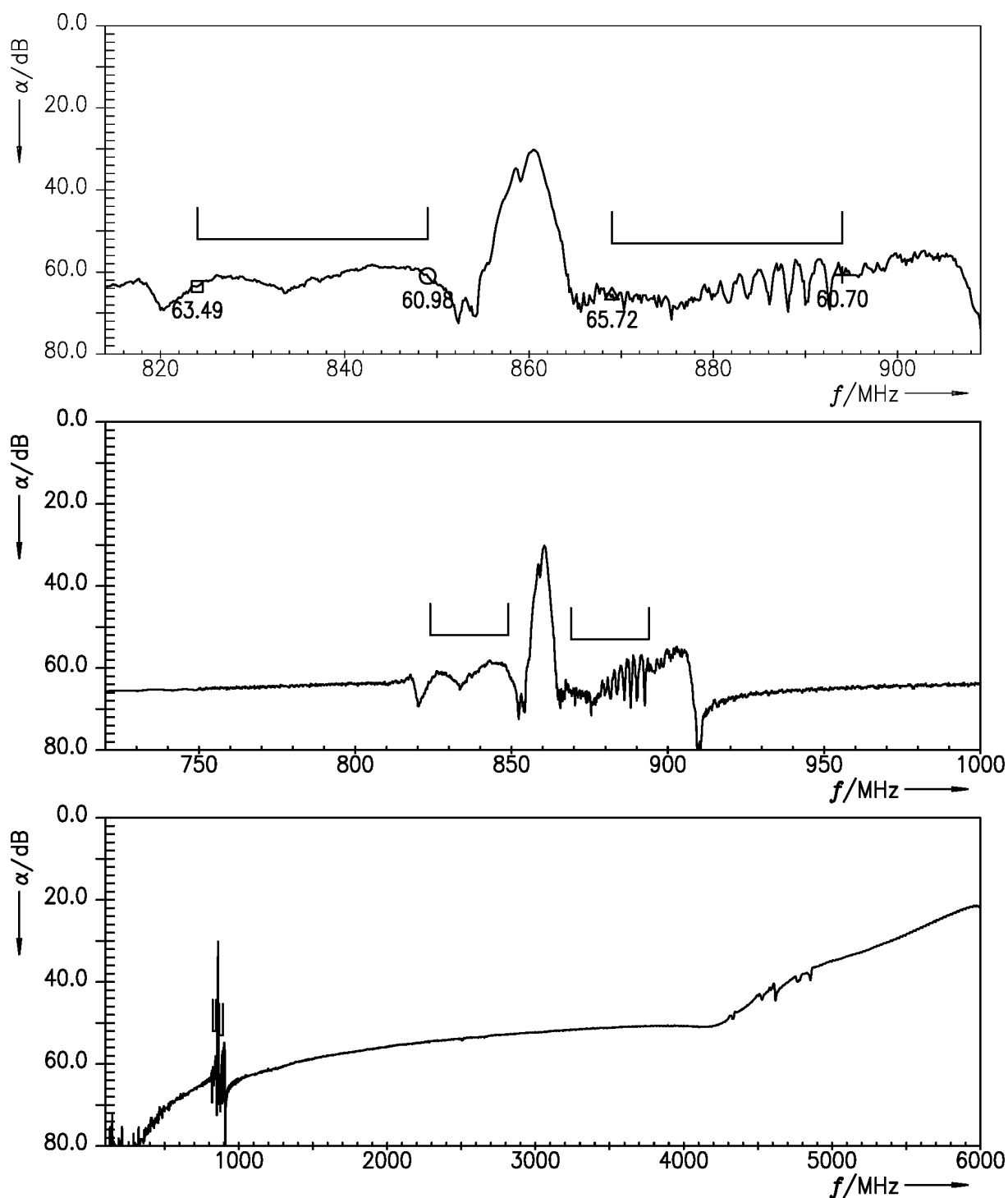


Figure 6: Isolation TX – RX.

9 Reflection coefficients

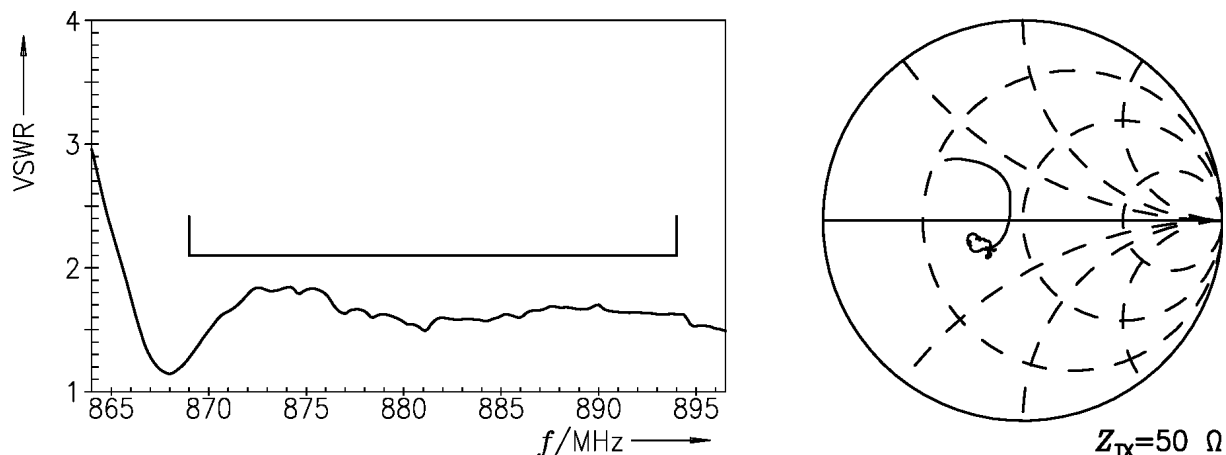


Figure 7: Reflection coefficient at TX port.

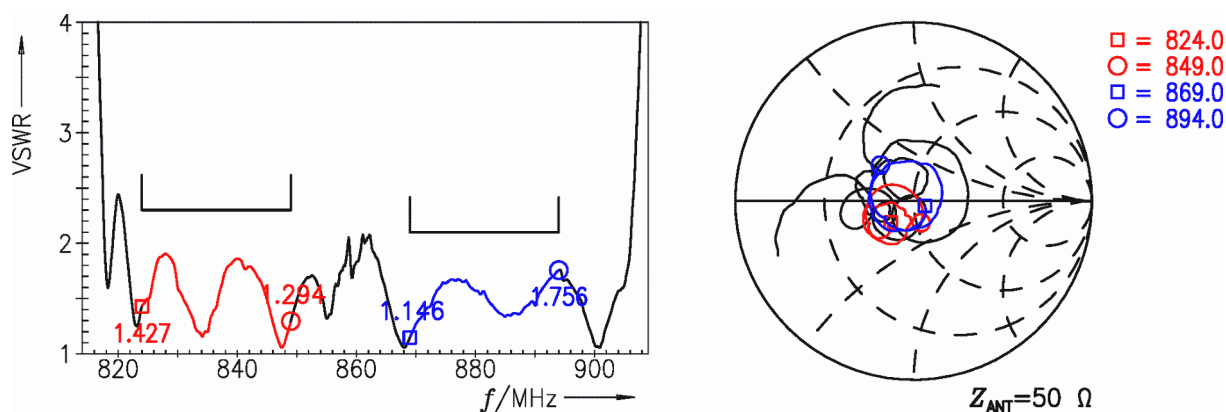


Figure 8: Reflection coefficient at ANT port.

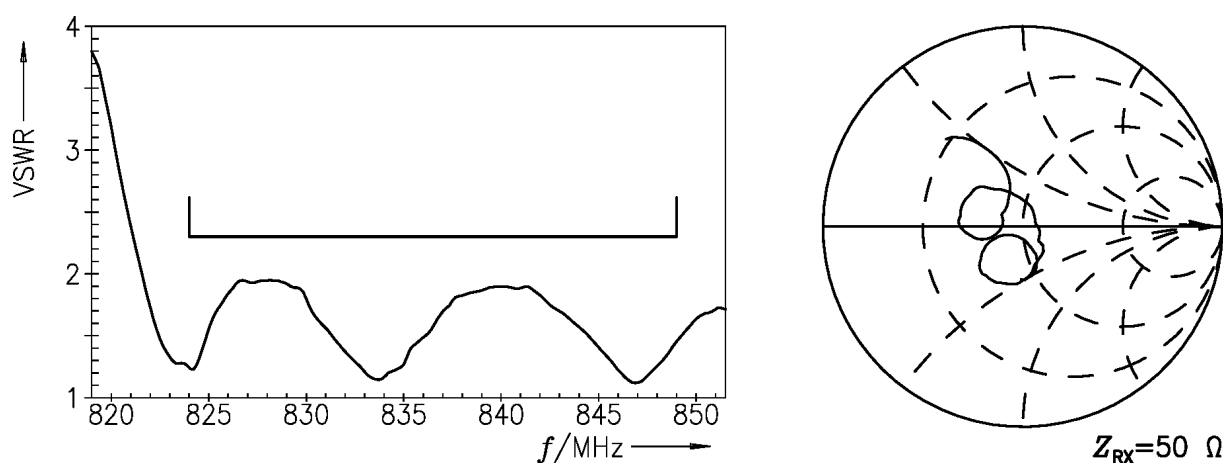


Figure 9: Reflection coefficient at RX port.

10 EVMs

10.1 TX – ANT

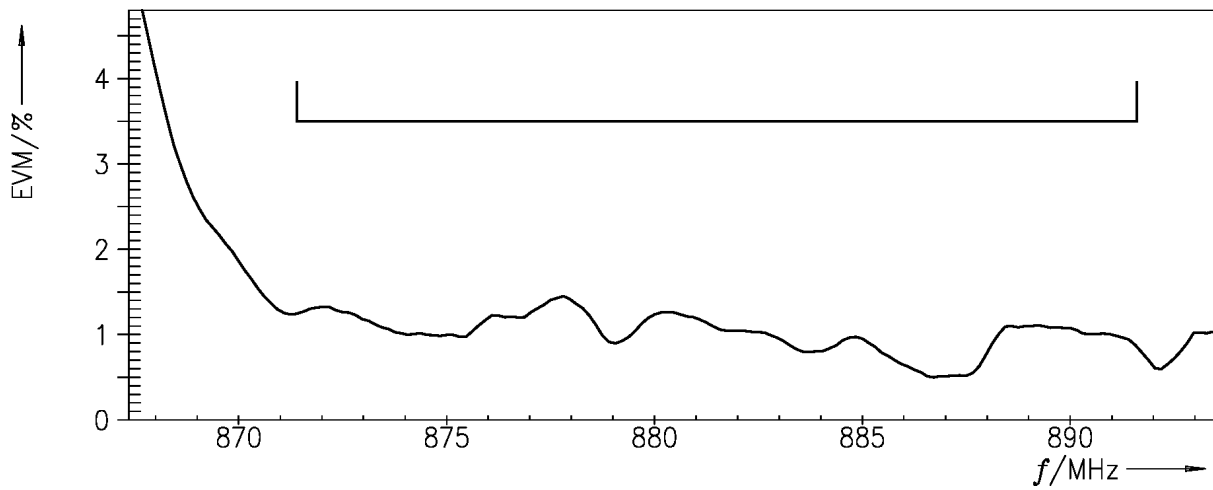


Figure 10: Error vector magnitude TX – ANT.

10.2 ANT – RX

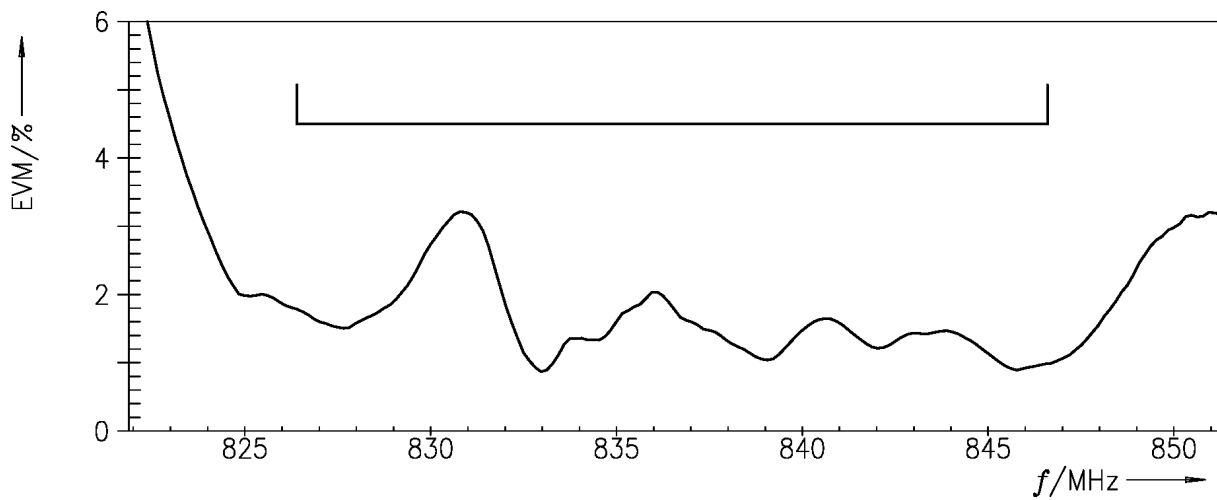


Figure 11: Error vector magnitude ANT – RX.

11 Packing material

11.1 Tape

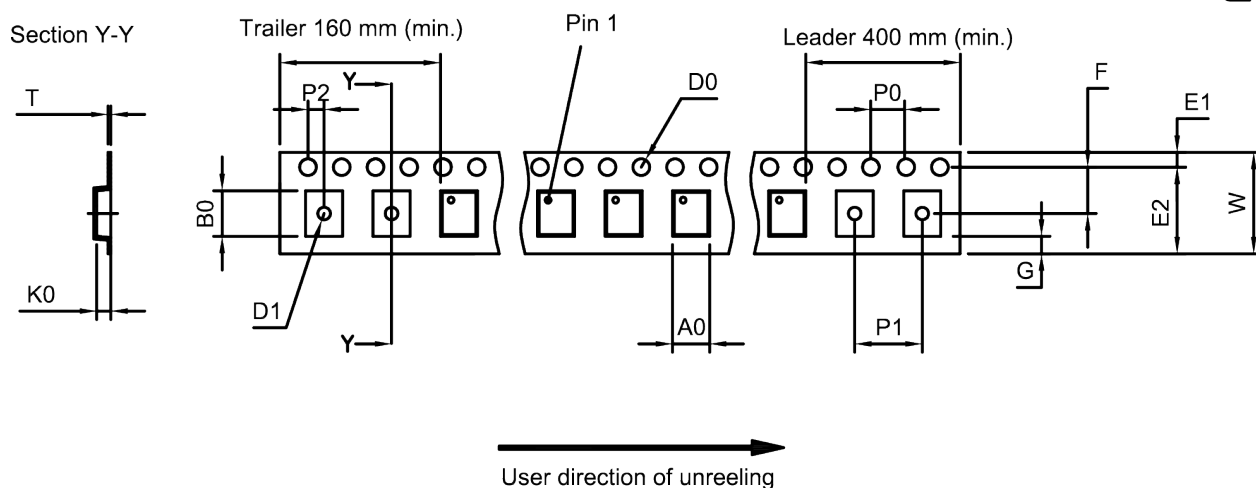


Figure 12: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

| | |
|-------|--------------------|
| A_0 | 2.25 ± 0.05 mm |
| B_0 | 2.75 ± 0.05 mm |
| D_0 | $1.5^{+0.1/-0}$ mm |
| D_1 | 1.0 mm (min.) |
| E_1 | 1.75 ± 0.1 mm |

| | |
|-------|-------------------|
| E_2 | 6.25 mm (min.) |
| F | 3.5 ± 0.05 mm |
| G | 0.75 mm (min.) |
| K_0 | 0.6 ± 0.05 mm |
| P_0 | 4.0 ± 0.1 mm |

| | |
|-------|----------------------|
| P_1 | 4.0 ± 0.1 mm |
| P_2 | 2.0 ± 0.05 mm |
| T | 0.25 ± 0.03 mm |
| W | $8.0^{+0.3/-0.1}$ mm |

Table 1: Tape dimensions.

11.2 Reel with diameter of 180 mm

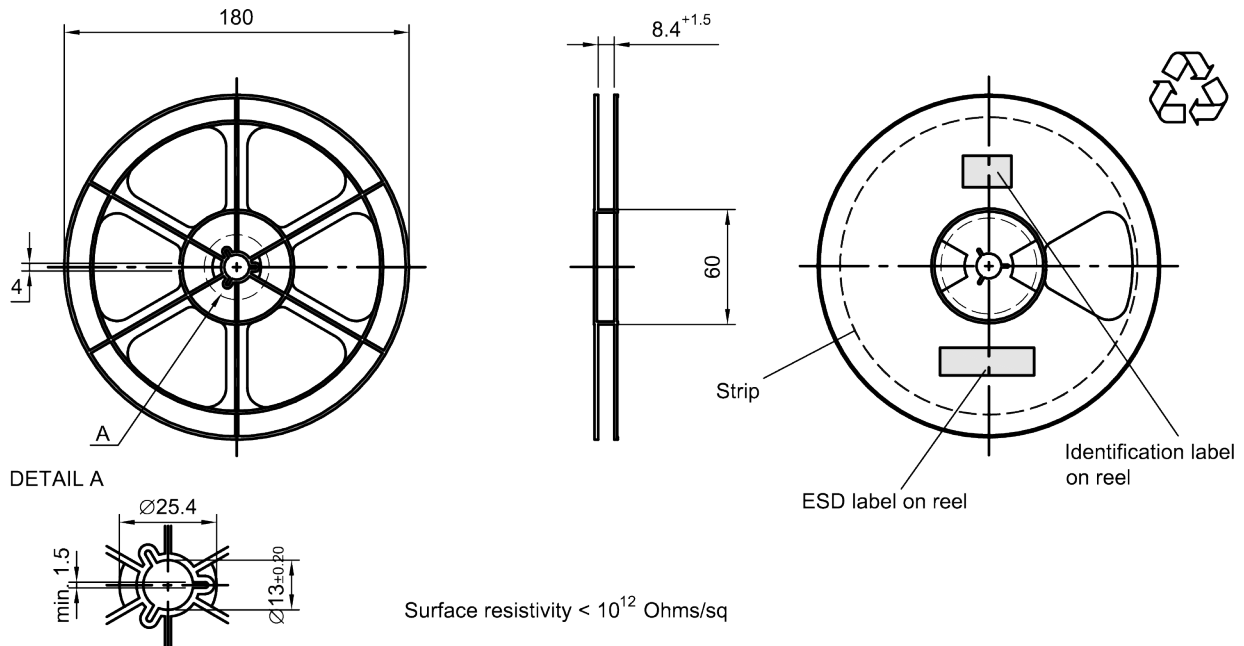


Figure 13: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]

X = 220+5

Y = 235+5

Sealing area 10±3

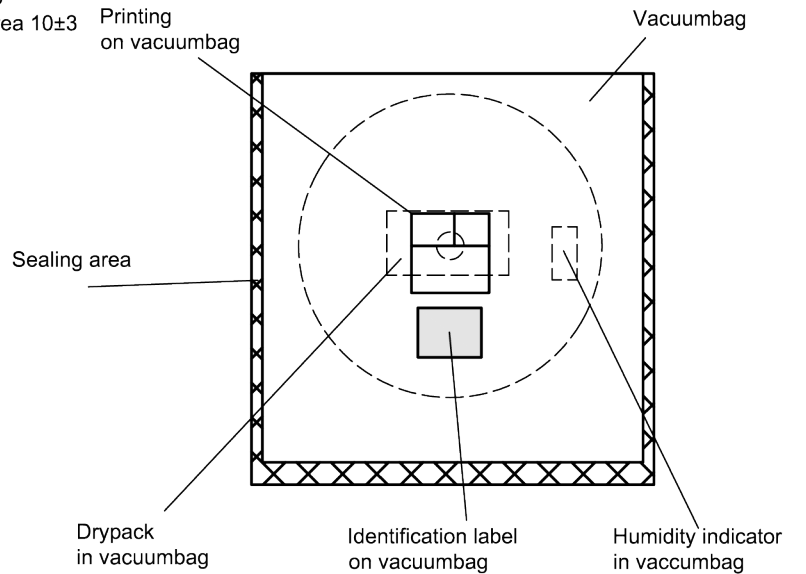


Figure 14: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

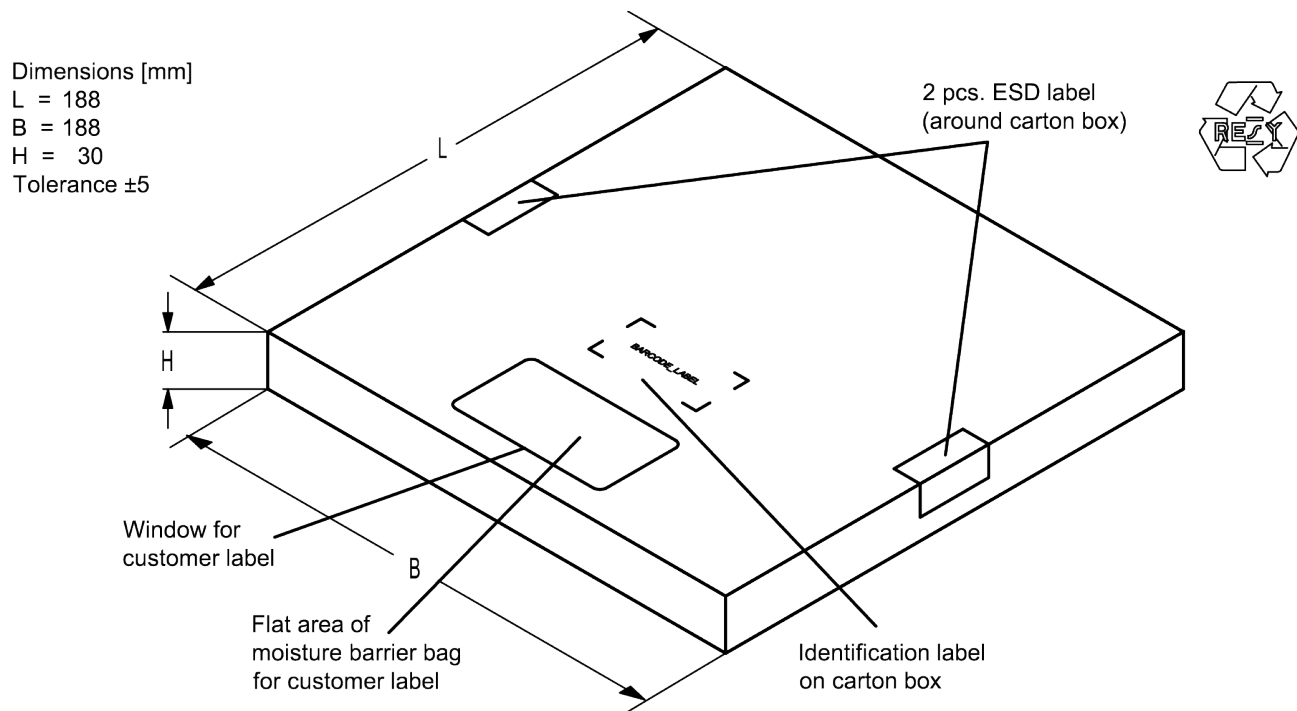


Figure 15: Drawing of folding box for reel with diameter of 180 mm.

12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

| | | |
|---|----|-------------|
| 16J | => | 1234 |
| $1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0$ | = | 1234 |

The BASE32 code for product type B8013 is 7TD.

■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

| | | |
|---|----|--------------|
| 5UY | => | 12345 |
| $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0$ | = | 12345 |

| Adopted BASE32 code for type number | | | |
|-------------------------------------|-------------|---------------|-------------|
| Decimal value | Base32 code | Decimal value | Base32 code |
| 0 | 0 | 16 | G |
| 1 | 1 | 17 | H |
| 2 | 2 | 18 | J |
| 3 | 3 | 19 | K |
| 4 | 4 | 20 | M |
| 5 | 5 | 21 | N |
| 6 | 6 | 22 | P |
| 7 | 7 | 23 | Q |
| 8 | 8 | 24 | R |
| 9 | 9 | 25 | S |
| 10 | A | 26 | T |
| 11 | B | 27 | V |
| 12 | C | 28 | W |
| 13 | D | 29 | X |
| 14 | E | 30 | Y |
| 15 | F | 31 | Z |

| Adopted BASE47 code for lot number | | | |
|------------------------------------|-------------|---------------|-------------|
| Decimal value | Base47 code | Decimal value | Base47 code |
| 0 | 0 | 24 | R |
| 1 | 1 | 25 | S |
| 2 | 2 | 26 | T |
| 3 | 3 | 27 | U |
| 4 | 4 | 28 | V |
| 5 | 5 | 29 | W |
| 6 | 6 | 30 | X |
| 7 | 7 | 31 | Y |
| 8 | 8 | 32 | Z |
| 9 | 9 | 33 | b |
| 10 | A | 34 | d |
| 11 | B | 35 | f |
| 12 | C | 36 | h |
| 13 | D | 37 | n |
| 14 | E | 38 | r |
| 15 | F | 39 | t |
| 16 | G | 40 | v |
| 17 | H | 41 | \ |
| 18 | J | 42 | ? |
| 19 | K | 43 | { |
| 20 | L | 44 | } |
| 21 | M | 45 | < |
| 22 | N | 46 | > |
| 23 | P | | |

Table 2: Lists for encoding and decoding of marking.

13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

| | |
|--------------------------------------|--|
| ramp rate | ≤ 3 K/s |
| preheat | 125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s |
| $T > 220\text{ °C}$ | 30 s to 70 s |
| $T > 230\text{ °C}$ | min. 10 s |
| $T > 245\text{ °C}$ | max. 20 s |
| $T \geq 255\text{ °C}$ | – |
| peak temperature T_{peak} | 250 °C +0/-5 °C |
| wetting temperature T_{min} | 230 °C +5/-0 °C for 10 s ± 1 s |
| cooling rate | ≤ 3 K/s |
| soldering temperature T | measured at solder pads |

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

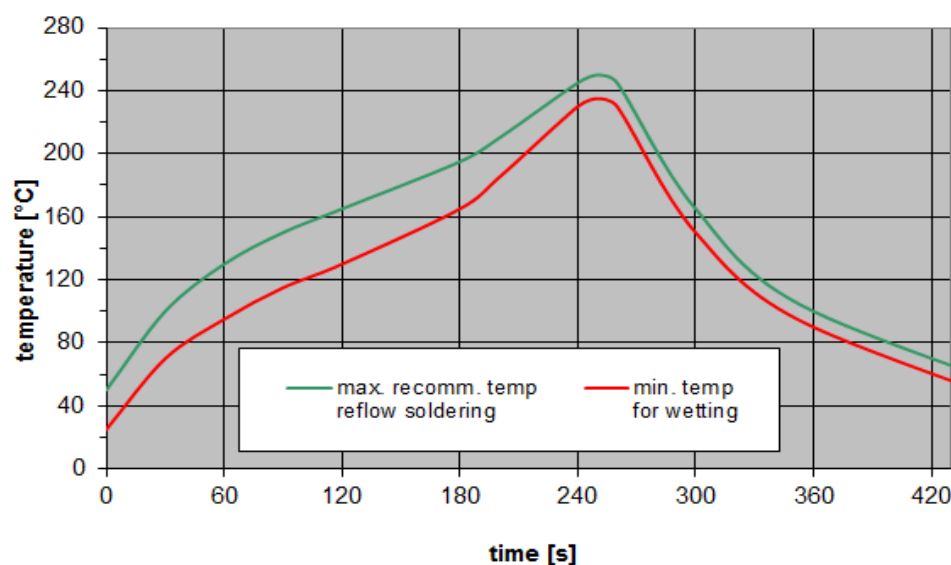


Figure 16: Recommended reflow profile for convection and infrared soldering – lead-free solder.

14 Annotations

14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.3 Ordering codes and packing units

| Ordering code | Packing unit |
|-----------------|--------------|
| B39881B8013P810 | 5000 pcs |

Table 4: Ordering codes and packing units.

15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

16 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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